



SPECIFICATIONS:  
 Contact Resistance : 30m $\Omega$  max  
 Insulation Resistance : 100M $\Omega$  min. at DC 500V  
 Dielectric Withstand Voltage : AC 500V for one minute  
 Remark:  $\Delta$ : The Most Important Dimension

NO.	Description	Material	Q'TY	Finish
10.	Back Cover	PBT+15%G	1	Black Color
9.	Housing	PBT	1	Black Color
8.	Break Terminal	0.25T Phosphor Bronze	1	Silver Plated
7.	Separator Terminal	0.3T Brass	1	Silver Plated
6.	Insulator	POM	2	White Color
5.	Break Terminal	0.25T Phosphor Bronze	1	Silver Plated
4.	Separator Spring	0.3T Brass	1	Silver Plated
3.	Ring Spring	0.25T Phosphor Bronze	1	Silver Plated
2.	Tip Spring	0.35T Phosphor Bronze	1	Silver Plated
1.	Earth Spring	0.25T Phosphor Bronze	1	Silver Plated

(1) Resistance to soldering heat test.

The jack terminal shall be dipped in solder under the condition as specified below.

(a) The terminal for a printed circuit board : Temperature of solder : 260 $^{\circ}$ C $\pm$ 5 $^{\circ}$ C

Dip time : 5 $\pm$ 1 seconds

(b) The terminal for a lead wire : Temperature of solder : 350 $^{\circ}$ C $\pm$ 10 $^{\circ}$ C

Dip time : 3 $\pm$ 0.5 seconds

(2) Test Condition : (a) Solder time : 3 $\pm$ 0.5sec

(b) Solder pot : 230 $\pm$ 5 $^{\circ}$ C

Pin Hole Layout  
(Jack Bottom View)

DATE	DWN	CHKD
12.03.2005	易愛娣	陳英光

PART NAME : 3.5 $\phi$  PHONE JACK

TOLERANCE :  $\pm$ 0.3mm UNLESS OTHERWISE SPECIFIED

UNIT: mm

**SHOGYO INTERNATIONAL CORP.**

# SCJ340P00(\*)S0BNPG